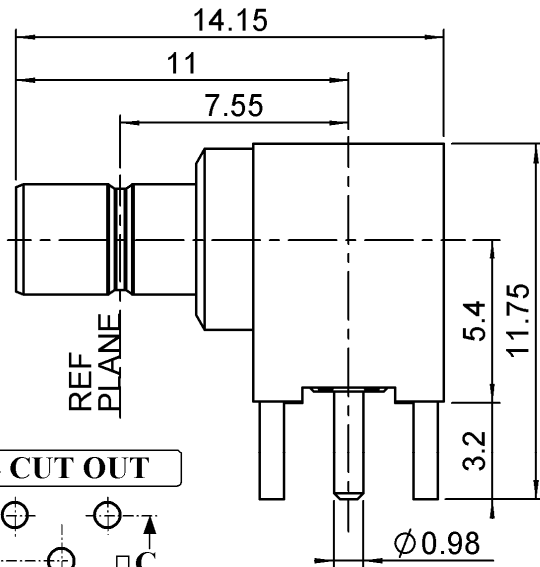
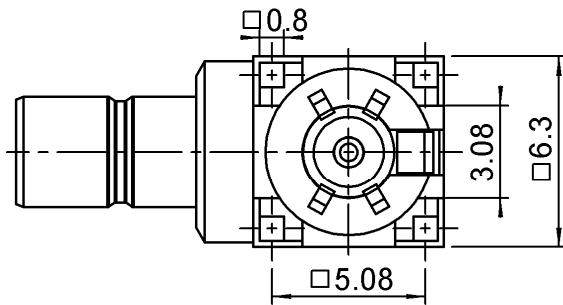


R/A MALE RECEPTACLE FOR PCB

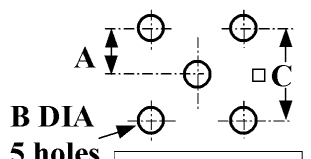
**R114.665.230**

PIN IN PASTE VERSION

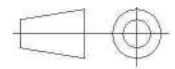
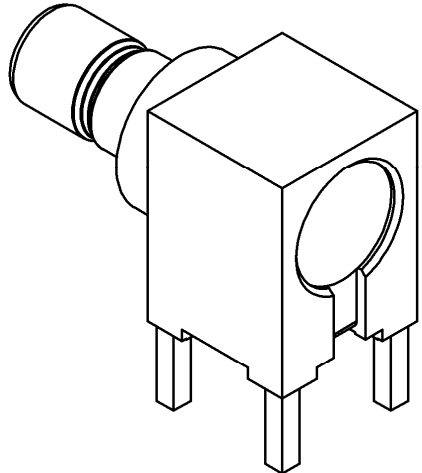
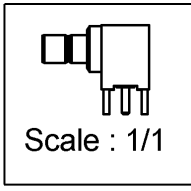
Series : SMB



PANEL CUT OUT



	mm	
	Maxi	mini
A	2.59	2.49
B	1.4	1.3
C	5.16	5



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BRASS	GOLD 1.3 OVER NICKEL 2.54 OVER COPPER 3
OUTER CONTACT		
INSULATOR	PTFE	
GASKET		
OTHERS PARTS	BRASS	GOLD 0.2 OVER NICKEL 2-
-	-	-
-	-	-

Issue : 0824 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**R/A MALE RECEPTACLE FOR PCB**

**R114.665.230**

**PIN IN PASTE VERSION**

Series : **SMB**

**PACKAGING**

**SPECIFICATION**

Standard	Unit	Other
<b>100</b>	<b>'W' option</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>0-4</b>	GHz
VSWR	<b>*1.20 + 0.0000</b>	x F(GHz) Maxi
Insertion loss	<b>*0.25</b>	$\sqrt{F(GHz)}$ dB Maxi
RF leakage	- ( <b>NA</b> )	- F(GHz)) dB Maxi
Voltage rating	<b>335</b>	Veff Maxi
Dielectric withstanding voltage	<b>1000</b>	Veff mini
Insulation resistance	<b>1000</b>	M $\Omega$ mini

Operating temperature	<b>-65/+165</b>	$^{\circ}$ C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**OTHER CHARACTERISTICS**

Assembly instruction

Others :

\*coaxial transmission line only  
compliant with MSL 1

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating end	<b>10</b>	N mini
Axial force – Opposite end	<b>10</b>	N mini
Torque	<b>NA</b>	N.cm mini
Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>500</b>	Cycles mini
Weight	<b>2.8000</b>	g

Issue : 0824 A

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**R/A MALE RECEPTACLE FOR PCB**

**R114.665.230**

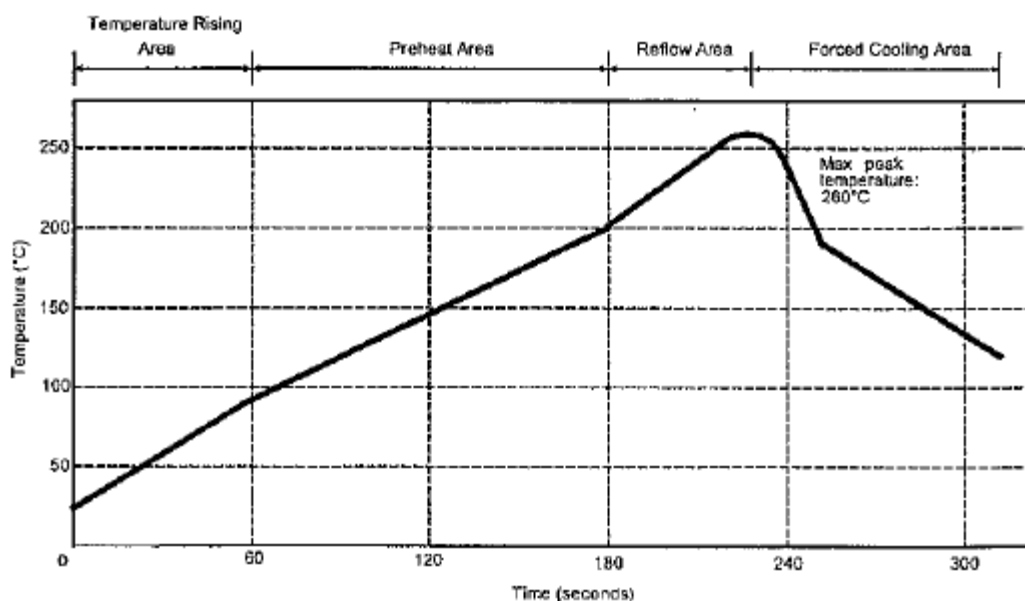
**PIN IN PASTE VERSION**

Series : **SMB**

**SOLDER PROCEDURE**

1. Deposition of solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application.  
We recommend a low residue flux.  
We advise a thickness of 150 microns mini (0.005 inch).  
Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.  
Video camera is recommended for the positioning of the component.  
Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.  
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

**TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1-4	° C/sec
Max Peak Temperature	260	° C
Max dwell time @260° C	10	sec
Min dwell time @235° C	20	sec
Max dwell time @235° C	60	sec
Temperature drop in cooling Area	-1 to-4	° C/sec
Max dwell time above 100° C	420	sec

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